

The Third International Conference on Electronics and Software Science (ICESS2017)

July 31 - August 2, 2017

Takamatsu Sunport Hall Building

Takamatsu, Japan

<http://sdiwc.net/conferences/3rd-international-electronics-software-science/>



You are invited to participate in The Third International Conference on Electronics and Software Science (ICESS2017) that will be held in Takamatsu, Japan, on July 31 - August 2, 2017. The event will be held over three days, with presentations delivered by researchers from the international community, including presentations from keynote speakers and state-of-the-art lectures.

The conference welcome papers on the following (but not limited to) research topics:

- Advanced Power System and Control System
- Analog and digital circuit Design
- Automobile Engineering
- Broad Band Communication
- Communication Computer and Intelligent Communication
- Control and Robotics
- Disaster Prevention Engineering
- E-Healthcare System
- Electromagnetics and Photonics
- Ergonomics and Application
- Expert Systems and Artificial Intelligence Techniques
- Feedback Control Systems
- High Voltage Engineering
- Information systems and network security
- Kansei Engineering
- Measurements and Instrumentation
- Mechatronics and Avionics
- Medical Engineering
- Nano Devices and Integrated Systems
- Non Conventional Energy Resources
- Optical Networks & communication
- Power Electronics
- Power Electronics & Electric Drives
- Power Electronics and Energy Efficient Drives
- Power Quality Improvement Techniques
- Power Systems
- Processing and Multimedia, Biomedical Imaging
- Remote sensing and satellite communication
- RF and Microwave Engineering
- Sensor technology & Virtual Instrumentation
- Server Virtualization Technology
- Soft Computing Techniques in Power Systems
- Software for Life Science
- Software for Material Science
- System Modeling & Simulation
- Systems Science and Signal Processing
- VLSI technology & Design
- Affective Computing

Submission Deadline: Open from now until June 30, 2017

Notification of Acceptance: 4-7 weeks from the Submission Date

Camera Ready Submission: July 21, 2017

Registration Deadline: July 21, 2017

Takamatsu, Japan

